



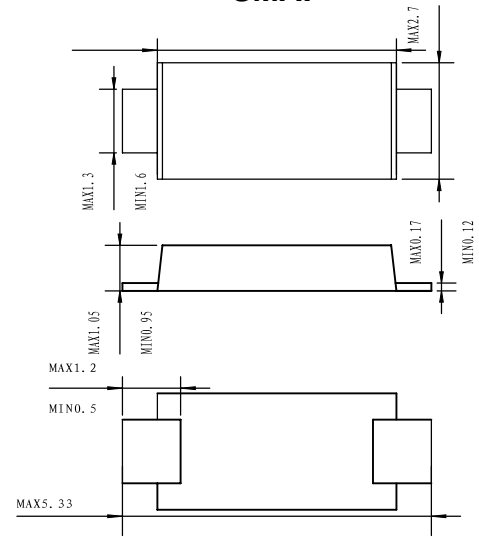
SMAF

### FEATURES

- Low profile package
- For surface mounted applications
- Built-in strain relief, ideal for automated placement
- High temperature soldering: 260°C/10 seconds at terminals
- Plastic package has underwriters, laborator flammability classification 94V-0

### MECHANICAL DATA

- Case :JEDEC SMAFL, molded plastic over passivated chip
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: color band denotes cathode end



### Maximum Ratings (@TA = 25°C unless otherwise specified)

Characteristic	Symbol	RS1A AF	RS1B AF	RS1D AF	RS1G AF	RS1J AF	RS1K AF	RS1M AF	UNITS
<b>Marking code</b>		<b>RS1A</b>	<b>RS1B</b>	<b>RS1D</b>	<b>RS1G</b>	<b>RS1J</b>	<b>RS1K</b>	<b>RS1M</b>	<b>UNITS</b>
Maximum recurrent peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current $T_L=90^\circ\text{C}$	$I_{F(AV)}$	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load	$I_{FSM}$	30							A

### Thermal Characteristics

Characteristic	Symbol	RS1A AF	RS1B AF	RS1D AF	RS1G AF	RS1J AF	RS1K AF	RS1M AF	UNITS
Typical junction capacitance (Note2)	$C_J$	10					7.0		p F
Typical thermal resistance (Note3)	$R_{\theta JL}$	17							$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_J T_{STG}$	- 55 ----- + 150							$^\circ\text{C}$

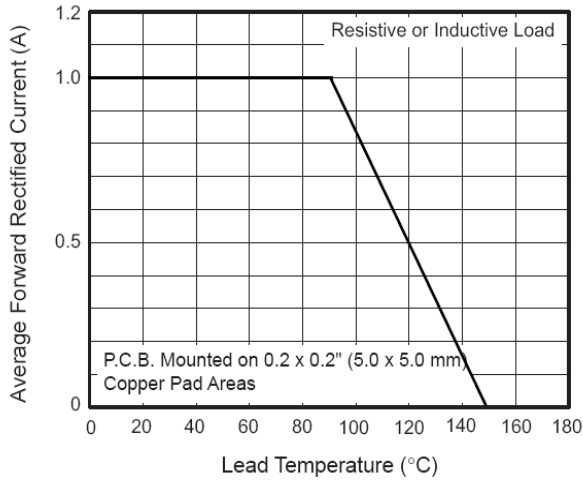
### Electrical Characteristics (@TA = 25°C unless otherwise specified)

Characteristic	Symbol	RS1A AF	RS1B AF	RS1D AF	RS1G AF	RS1J AF	RS1K AF	RS1M AF	UNITS	
Maximum instantaneous forward voltage at 1.0 A	$V_F$	1.30							V	
Maximum reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	$I_R$					5.0		50.0		$\mu\text{A}$
Typical reverse recovery time (Note1)	$t_{rr}$	150				250		500		ns

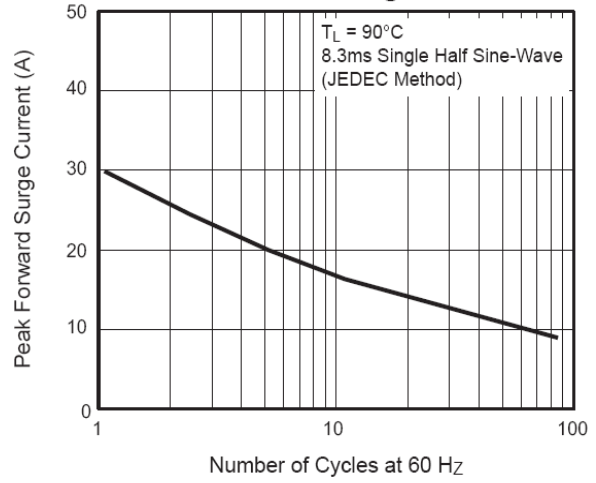
- NOTE: 1.Reverse recovery time test conditions:  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{rr}=0.25\text{A}$   
 2. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts  
 3. Thermal resistance from junction to lea



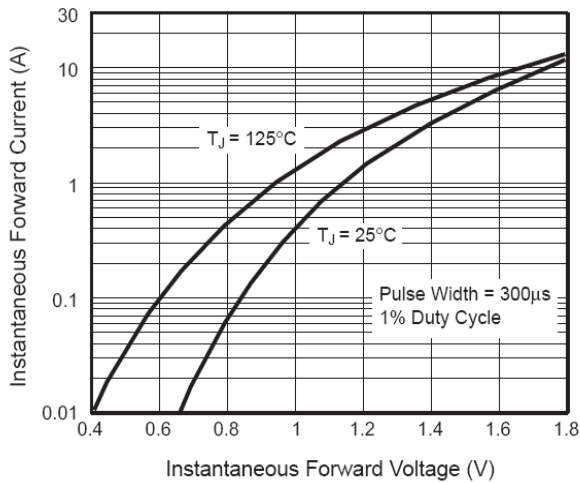
**Fig. 1 — Forward Current Derating Curve**



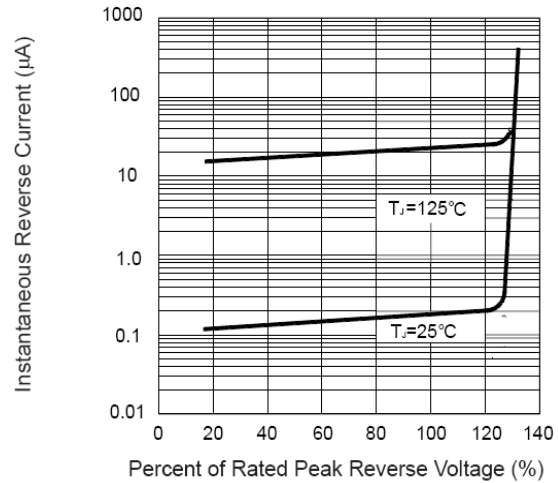
**Fig. 2 — Maximum Non-Repetitive Peak Forward Surge Current**



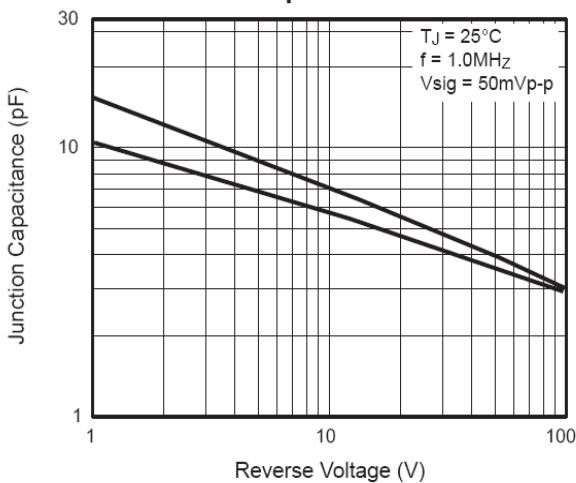
**Fig. 3 — Typical Instantaneous Forward Characteristics**



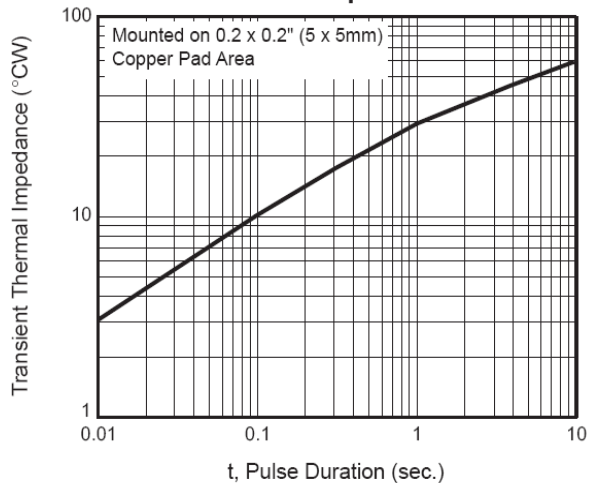
**Fig. 4 — Typical Reverse Characteristics**



**Fig. 5 — Typical Junction Capacitance**



**Fig. 6 — Typical Transient Thermal Impedance**



PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
SMAF	5000/REEL	80000	36X30.6X31	12.00	11.00